

4

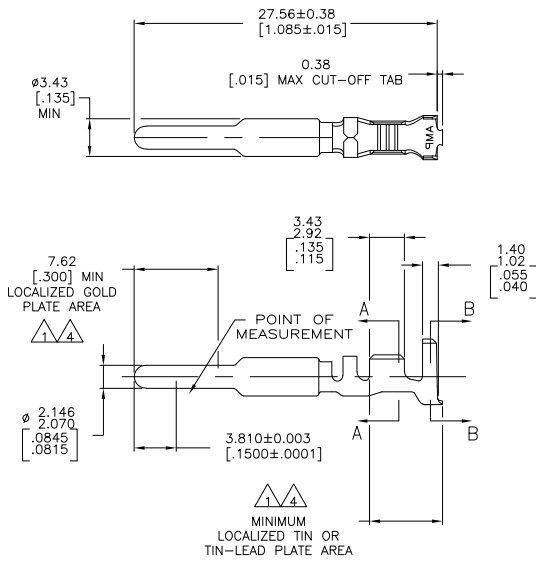
3

2

1

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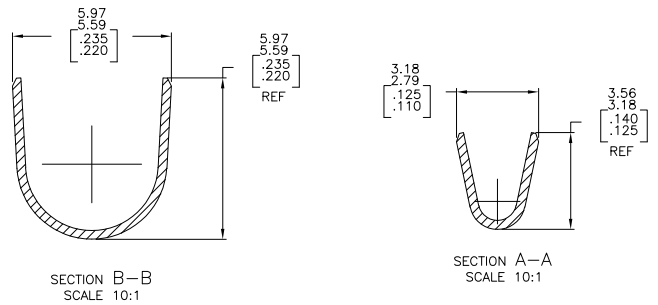
LOC	DIST	REVISIONS		
F	LTR	DESCRIPTION	DATE	BY
CM	0			
F		EC 0038 0215 05	19SEP05	BSV/RCJ



△ 0.00076[.000030] MIN GOLD AT POINT OF MEASUREMENT IN THE LOCALIZED GOLD PLATE AREA, 0.00127[.000050] MIN TIN-LEAD IN THE TIN-LEAD PLATE AREA, 0.00127[.000050] MIN NICKEL UNDERPLATE ON ENTIRE CONTACT.

2. WIRE RANGE: 0.5-2mm<sup>2</sup> [20-14] AWG. INSULATION RANGE: 3.30-5.08[.130-.200] DIA.
3. DIMENSIONS IN BRACKETS ARE IN INCHES.

△ 0.00076[.000030] MIN GOLD AT POINT OF MEASUREMENT IN THE LOCALIZED GOLD PLATE AREA, 0.00127[.000050] MIN TIN IN TIN PLATE AREA, 0.00127[.000050] MIN NICKEL UNDERPLATE ON ENTIRE CONTACT.



GOLD	△	0.30 [0.012]	BRASS	1-770255-0
GOLD	△	0.30 [0.012]	BRASS	770255-2
PRE-TIN		0.30 [0.012]	BRASS	770255-1
FINISH			MATERIAL	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.		DRW	K. SALMON	230092	Tyco Electronics Corporation
		CHK	S. SWING	230092	Harrisburg, PA 17105-3608
		APP	M. TRULL	01AP93	
		PRODUCT SPEC			
		APPLICATION SPEC			
		WEIGHT			
		SIZE	A2	00779	C=770255
		CUSTOMER DRAWING			



AMP 1471-9 REV 31MM2000

770255

A

RESTRICTED TO

REV F